



# MULTILAYER CERAMIC CAPACITORS Ultra-small Series (6.3V to 25V) 01005 Size NP0, X7R & X5R Dielectrics RoHS Compliance

\*Contents in this sheet are subject to change without prior notice.



## **1. INTRODUCTION**

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

01R5 MLCC is performed by high precision technology achieve high capacitance in unit size and ensure the stability and reliability of products.

## 2. FEATURES

- b. High capacitance in unit size.
- c. High precision dimensional tolerances.
- d. Suitable used in high-accuracy automatic mounting machine.

## **3. APPLICATIONS**

- a. Miniature microwave module.
- b. Portable equipments (ex. Mobile phone, PDA).
- c. High frequency circuits.

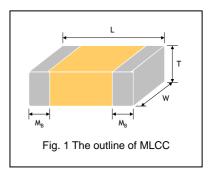
## 4. HOW TO ORDER

<u>01R5</u>	<u>N</u>	<u>100</u>	<u>C</u>	<u>160</u>	<u>C</u>	I
<u>Size</u>	Dielectric	Capacitance	<u>Tolerance</u>	Rated voltage	<u>Termination</u>	Packaging
Inch (mm) 01R5 = 01005 (0402)	N=NP0 (C0G) B=X7R X=X5R	Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: 0R5=0.5pF 1R0=1.0pF 100=10x10 <sup>0</sup> =10pF	A=±0.05pF B=±0.1pF C=±0.25pF D=±0.5pF J=±5% K=±10% M=±20%	Two significant digits followed by no. of zeros. And R is in place of decimal point. <b>6R3</b> =6.3 VDC <b>100</b> =10 VDC <b>160</b> =16 VDC <b>250</b> =25 VDC	<b>C</b> =Cu/Ni/Sn	T=7" reeled



# **5. EXTERNAL DIMENSIONS**

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Syr	nbol	М <sub>в</sub> (mm)
01R5 (0402)	0.40±0.02	0.20±0.02	0.20±0.02	V	0.10±0.03
* Reflow soldering only.					



# **6. GENERAL ELECTRICAL DATA**

Size	01R5				
Dielectric	NP0	X7R	X5R		
Capacitance*	0.2pF to 100pF	100pF to 1000pF	1000pF to 0.1µF		
Capacitance tolerance**	Cap≤5pF: A (±0.05pF), B (±0.1pF), C (±0.25pF) 5pF <cap<10pf: C (±0.25pF), D (±0.5pF) Cap≥10pF: J (±5%)</cap<10pf: 	K (±10%), M (±20%)			
Rated voltage (WVDC)	16V, 25V	10V	6.3V, 10V		
DF / Q <sup>#1</sup>	Cap<30pF, Q≥400+20C Cap≥30pF, Q≥1000	≤5 %	≤10 %		
Insulation resistance at Ur	≥10GΩ or RxC≥500Ω*F	≥10GΩ or RxC≥500Ω*F whichever is less			
Operating temperature	-55 to +125°C	-55 to +125°C	-55 to +85°C		
Capacitance change	±30ppm ±15		/ 0		
Termination	Ni/Sn (lead-free termination)				

\* Measured at 30~70% related humidity.

NP0: Apply 0.5~5Vrms, 1.0MHz±10% at the condition of 25°C ambient temperature.

X7R: Apply 1.0±0.2Vrms, 1.0kHz±10%, at 25°C ambient temperature. X5R: Apply 0.5±0.2Vrms or 1.0±0.2Vrms<sup>#1</sup>, 1.0kHz±10%, at the condition of 25°C ambient temperature.

\*\* Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in ambient condition for 24±2 hours before measurement.

#1: Please refer to "RELIABILITY TEST CONDITIONS AND REQUIREMENTS" for detail



# 7. CAPACITANCE RANGE

SIZE		01	R5
	DIELECTRIC	N	P0
RAT	ED VOLTAGE (VDC)	16	25
	0.2pF (0R2)	V	V
	0.3pF (0R3)	V	V
	0.4pF (0R4)	V	V
	0.5pF (0R5)	V	V
	1.0pF (1R0)	V	V
	1.5pF (1R5)		V
	2.0pF (2R0)		V
	3.0pF (3R0)	V	V
	4.0pF (4R0)	V	V
	5.0pF (5R0)	V	V
-	6.0pF (6R0)	V	V
ů.	7.0pF (7R0)	V	V
itaı	8.0pF (8R0)	V	V
ac	9.0pF (9R0)	V	V
Capacitance	10pF (100)	V	V
0	12pF (120)	•	
	15pF (150) 18pF (180)	V	V V
	22pF (220)	V	V
	27pF (220)	V	V
	33pF (330)		V
	39pF (390)	V	V
	47pF (470)	V	V
	56pF (560)	V	V
	68pF (680)	V	V
	82pF (820)		V
	100pF (101)	V	V

	SIZE	01R5
	DIELECTRIC	X7R
RA	TED VOLTAGE (VDC)	10
	100pF (101)	V
JCe	150pF (151)	V
itaı	220pF (221)	V
Capacitance	330pF (331)	V
Cal	470pF (471)	V
	1,000pF (102)	V

	SIZE	01	R5
	DIELECTRIC	X	ōR
RA	TED VOLTAGE (VDC)	6.3	10
	1,000pF (102)	V	V
	1,500pF (152)		V
	2,200pF (222)		V
	3,300pF (332)		V
Capacitance	4,700pF (472)		V
tan	6,800pF (682)		V
aci	0.010µF (103)	V	V
ap	0.015µF (153)		
Ű	0.022µF (223)	V	
	0.033µF (333)	V	
	0.047µF (473)	V	
	0.068µF (683)		
	0.10µF (104)	V	

1. The letter in cell is expressed the symbol of product thickness.

2. For more information about products with special capacitance

or other data, please contact WTC local representative.

# 8. PACKAGING DIMENSION AND QUANTITY

Size	Thickness (mm)/Symbol		Paper tape	
Size			7" reel	13" reel
01R5 (0402)	0.20±0.02	V	20,000	-

Unit: pieces



# 9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	ltem		Test Condition		Requirements		
1.	Visual and Mechanical			* No remarkable defect. * Dimensions to conform to individual specification sheet.			
2.	Capacitance	Class I: NP0 *		* Shall not	exceed the limits given in the detailed spec.		
3.	Q/ D.F. (Dissipation Factor)	Cap≤1000pF, 0.5~5Vrms, 1MHz±10% Cap>1000pF, 1.0±0.2Vrms, 1KHz±10% Class II: , X7R & X5R(≥10V) 1.0±0.2Vrms, 1KHz±10% Class II: , X5R(≤6.3V)		* NP0: Cap≥30pF, Q≥1000; Cap<30pF, Q≥400+20C X7R: ≤5.0 % X5R: ≤10 %			
4.	Dielectric Strength	0.5±0.2Vrms, 1kHz±10% * To apply voltage (≤100V) 250%. * Duration: 1 to 5 sec. * Charge and discharge current less than 50mA.			* No evidence of damage or flash over during test.		
5.	Insulation Resistance	To apply rated voltage for max. 120 sec.		* NP0, X7R: ≥10GΩ or RxC≥500Ω-F whichever is smaller. X5R: RxC≥50Ω-F			
6.	Temperature With no electrical load.						
	Coefficient	T.C.	Operating Temp		T.C.	Capacitance Change	
		NPO	-55~125°C at 25°C	-	NPO	Within ±30ppm/°C	
		X7R	-55~125°C at 25°C	-	X7R	Within ±15%	
		X5R	-55~ 85°C at 25°C		X5R	Within ±15%	
7.	Adhesive Strength of Termination	* Pressurizir * Test time: *	ng force:1N 10±1 sec.		* No remai	rkable damage or removal of the terminations.	
8.	Vibration	* Vibration f	requency: 10~55 Hz/min.		* No remarkable damage.		
	Resistance	<ul> <li>* Vibration frequency: 10~55 Hz/min.</li> <li>* Total amplitude: 1.5mm</li> <li>* Test time: 6 hrs. (Two hrs each in three mutually perpendicular directions.)</li> <li>* Measurement to be made after keeping at room temp. for 24±2 hrs.</li> </ul>		1	nge and Q/D.F.: To meet initial spec.		
9.	Solderability	1	nperature: 235±5°C ne: 2±0.5 sec.		95% min. coverage of all metalized area.		
10.	Bending Test	<ul> <li>Dipping time: 2±0.5 sec.</li> <li>The middle part of substrate shall be pressurized by means of the pressuring rod at a rate of about 1 mm per second until the deflection becomes 1 mm and then the pressure shall be maintained for 5±1 sec.</li> <li>Measurement to be made after keeping at room temp. for 24±2 hrs.</li> </ul>		ntil * Cap change:			

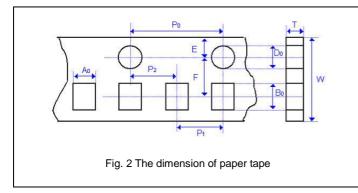


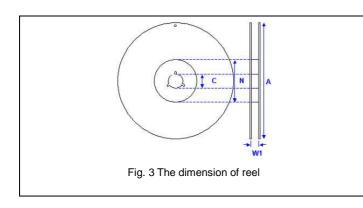
No.	Item	Test Condition	Requirements	
11.	Resistance to Soldering Heat Temperature	<ul> <li>* Solder temperature: 260±5°C</li> <li>* Dipping time: 10±1 sec</li> <li>* Preheating: 120 to 150°C for 1 minute before immerse the capacitor in a eutectic solder.</li> <li>* Before initial measurement (Class II only): Perform</li> <li>150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp.</li> <li>* Measurement to be made after keeping at room temp. for 24±2 hrs.</li> </ul>	<ul> <li>* No remarkable damage.</li> <li>* Cap change: NP0: within ±2.5% or ±0.25pF whichever is larger. X7R: within ±7.5%</li> <li>X5R: within ±15.0%</li> <li>Q/D.F., I.R. and dielectric strength: To meet initial requirements.</li> <li>* 25% max. leaching on each edge.</li> </ul>	
12.		<ul> <li>* Conduct the five cycles according to the temperatures and time.</li> <li>Step Temp. (°C) Time (min.) <ol> <li>Min. operating temp. +0/-3</li> <li>30±3</li> <li>Room temp.</li> <li>2-3</li> <li>Max. operating temp. +3/-0</li> <li>30±3</li> <li>Room temp.</li> <li>2-3</li> </ol> </li> <li>* Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp. * Measurement to be made after keeping at room temp. for 24±2 hrs.</li></ul>	<ul> <li>No remarkable damage.</li> <li>Cap change:</li> <li>NP0: within ±2.5% or ±0.25pF whichever is larger.</li> <li>X7R: within ±7.5%</li> <li>X5R: within ±15.0%</li> <li>Q/D.F., I.R. and dielectric strength: To meet initial requirements.</li> </ul>	
13.	Humidity (Steady State)	<ul> <li>* Test temp.: 40±2°C</li> <li>* Humidity: 90~95% RH</li> <li>* Test time: 500+24/-0hrs.</li> <li>*Before initial measurement (Class II only): Perform</li> <li>150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp.</li> <li>* Measurement to be made after keeping at room temp. for</li> <li>24±2 hrs.</li> </ul>	<ul> <li>* No remarkable damage.</li> <li>* Cap change: NP0: within ±5.0% or ±0.5pF whichever is larger. X7R: within ±12.5%</li> <li>X5R: within ±25.0%</li> <li>* Q/D.F. value: NP0: Cap≥30pF, Q≥350; 10pF≤Cap&lt;30pF, Q≥275+2.5C Cap&lt;10pF; Q≥200+10C</li> <li>X7R: ≤7.5%</li> <li>X5R: ≤20%</li> <li>* I.R.: NP0, X7R: ≥1GΩ or RxC≥50Ω-F whichever is smaller. X5R: RxC≥10Ω-F.</li> </ul>	
14.	Humidity Load (Damp Heat)	<ul> <li>* Test temp.: 40±2°C</li> <li>* Humidity: 90~95%RH</li> <li>* Test time: 500+24/-0 hrs.</li> <li>* To apply voltage : rated voltage.</li> <li>* Before initial measurement (Class II only): To apply test voltage for 1hr at 40°C and then set for 24±2 hrs at room temp.</li> <li>* Measurement to be made after keeping at room temp. for 24±2 hrs.</li> </ul>	* No remarkable damage. * Cap change: NP0: within ±7.5% or ±0.75pF whichever is larger. X7R: within ±15.0% X5R: within ±25.0%	
15.	High Temperature Load (Endurance)	<ul> <li>* Test temp.: NP0, X7R: 125±3°C X5R: 85±3°C</li> <li>* To apply voltage:</li> <li>(1) NP0, X7R : 200% of rated voltage</li> <li>(2) X5R: 10V : 150 % of rated voltage</li> <li>6.3V : 100 % of rated voltage</li> <li>* Test time: 1000+24/-0 hrs.</li> <li>*Before initial measurement (Class II only): To apply test voltage for 1hr at test temp. and then set for 24±2 hrs at room temp.</li> <li>*Measurement to be made after keeping at room temp. for 24±2 hrs</li> </ul>	<ul> <li>* No remarkable damage.</li> <li>* Cap change:</li> <li>NP0: within ±3.0% or ±0.3pF whichever is larger.</li> <li>X7R: within ±12.5%</li> <li>X5R: within ±25.0%</li> <li>* Q/D.F. value:</li> <li>NP0: Cap≥30pF, Q≥350; 10pF≤Cap&lt;30pF, Q≥275+2.5C</li> <li>Cap&lt;10pF; Q≥200+10C</li> <li>X7R: ≤7.5%</li> <li>X5R: ≤20%</li> <li>* I.R.:</li> <li>NP0, X7R: ≥1GΩ or RxC≥50Ω-F whichever is smaller.</li> <li>X5R: RxC≥10Ω-F.</li> </ul>	



## **APPENDIXES**

### Tape & reel dimensions

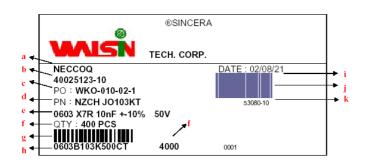




Size	01R5
Thickness	v
Ao	0.25 +/-0.05
B <sub>0</sub>	0.45 +/-0.05
т	≦0.50
K <sub>0</sub>	-
w	8.00 +/-0.10
Po	4.00 +/-0.10
10xP₀	40.00 +/-0.10
P <sub>1</sub>	2.00 +/-0.05
P <sub>2</sub>	2.00 +/-0.05
Do	1.55 +/-0.05
D <sub>1</sub>	-
E	1.75 +/-0.05
F	3.50 +/-0.05

Size	01R5
Reel size	7"
С	13.0+0.5/-0.2
<b>W</b> <sub>1</sub>	8.4+1.5/-0
Α	178.0±1.0
N	60.0+1.0/-0

#### Description of customer label

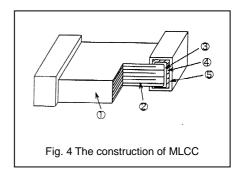


- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer
- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label



#### Constructions

No.	Nan	ne	NP0 / X7R / X5R
1	Ceramic material		BaTiO₃ based
2	Inner electrode		Ni
3		Inner layer	Cu
4	Termination	Middle layer	Ni
5		Outer layer	Sn (Matt)



#### Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

#### Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of  $N_2$  within oven are recommended.

